

J175 / J176 / MMBFJ175 / MMBFJ176 / MMBFJ177 P-Channel Switch

Description

This device is designed for low-level analog switching sample-and-hold circuits and chopper-stabilized amplifiers. Sourced from process 88.

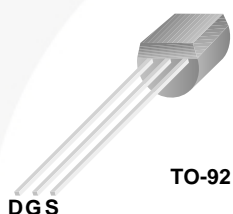


Figure 1. J175 / J176 Device Package

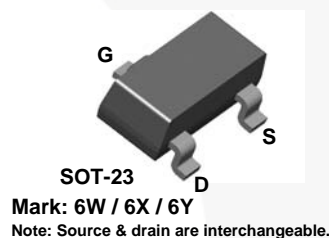


Figure 2. MMBFJ175 / 176 / 177 Device Package

Ordering Information

Part Number	Marking	Package	Packing Method
J175_D26Z	J175	TO-92 3L	Tape and Reel
J176_D74Z	J176	TO-92 3L	Ammo
MMBFJ175	6W	SOT-23 3L	Tape and Reel
MMBFJ176	6X	SOT-23 3L	Tape and Reel
MMBFJ177	6Y	SOT-23 3L	Tape and Reel

Absolute Maximum Ratings^{(1),(2)}

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V_{DG}	Drain-Gate Voltage	-30	V
V_{GS}	Gate-Source Voltage	30	V
I_{GF}	Forward Gate Current	50	mA
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to + 150	$^\circ\text{C}$

Notes:

- These ratings are based on a maximum junction temperature of 150°C .
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty cycle operations.

Thermal Characteristics⁽³⁾

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Max.		Unit
		J175 / J176	MMBFJ175 / MMBFJ176 / MMBFJ177	
P_D	Total Device Dissipation	350	225	mW
	Derate Above 25°C	2.8	1.8	mW/ $^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125		$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	556	$^\circ\text{C}/\text{W}$

Note:

- PCB size: FR-4 76 x 114 x 1.57 mm³ (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

Electrical Characteristics

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Conditions		Min.	Max.	Unit
Off Characteristics						
V _{(BR)GSS}	Gate-Source Breakdown Voltage	I _G = 1.0 μA, V _{DS} = 0		30		V
I _{GSS}	Gate Reverse Current	V _{GS} = 20 V, V _{DS} = 0			1.0	nA
V _{GS(off)}	Gate-Source Cut-Off Voltage	V _{DS} = -15 V, I _D = -10 nA	J175 / MMBFJ175	3.0	6.0	V
			J176 / MMBFJ176	1.0	4.0	
			MMBFJ177	0.8	2.5	
On Characteristics						
I _{DSS}	Zero-Gate Voltage Drain Current ⁽⁴⁾	V _{DS} = -15 V, I _{GS} = 0	J175 / MMBFJ175	-7.0	-60.0	mA
			J176 / MMBFJ176	-2.0	-25.0	
			MMBFJ177	-1.5	-20.0	
r _{DS(on)}	Drain-Source On Resistance	V _{DS} ≤ 0.1 V, V _{GS} = 0	J175 / MMBFJ175		125	Ω
			J176 / MMBFJ176		250	
			MMBFJ177		300	

Note:

4. Pulse test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2.0\%$.

Typical Performance Characteristics

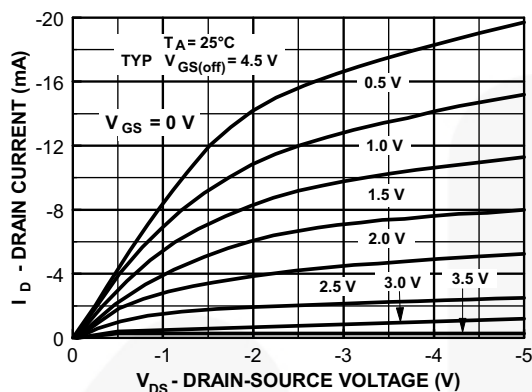


Figure 3. Common Drain-Source

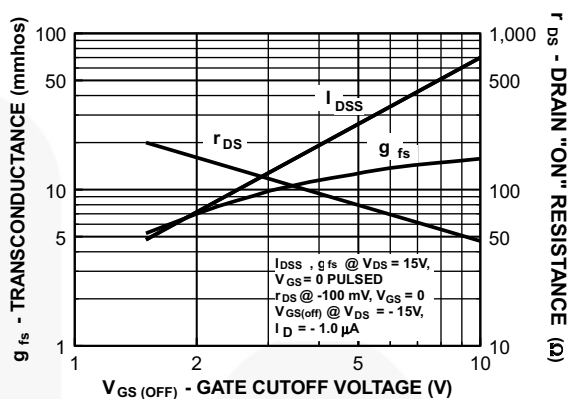


Figure 4. Parameter Interactions

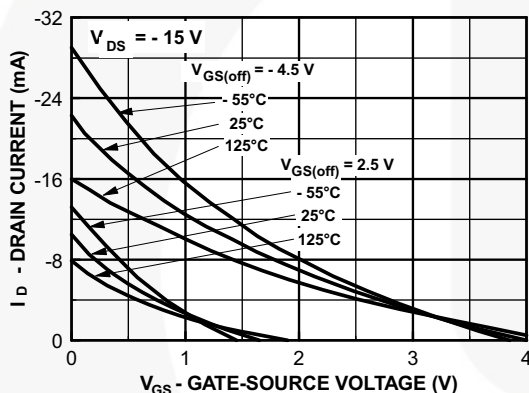


Figure 5. Transfer Characteristics

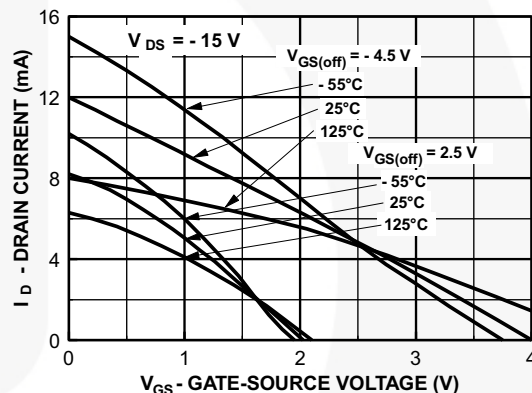


Figure 6. Transfer Characteristics

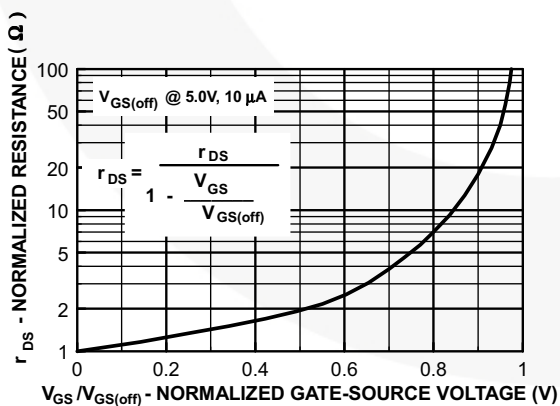


Figure 7. Normalized Drain Resistance vs. Bias Voltage

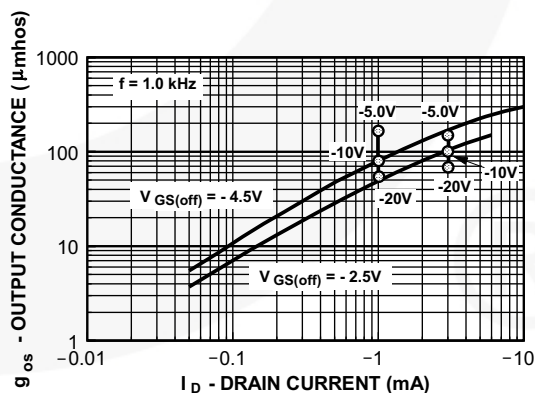


Figure 8. Output Conductance vs. Drain Current

Typical Performance Characteristics (Continued)

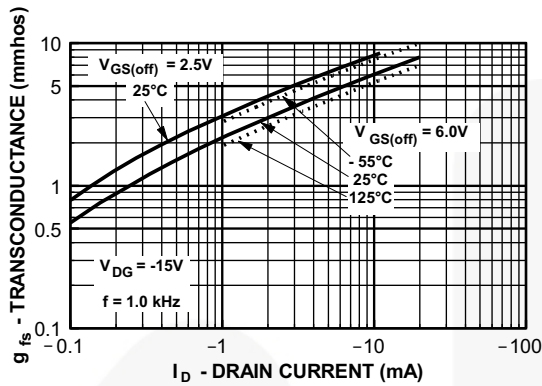


Figure 9. Transconductance vs. Drain Current

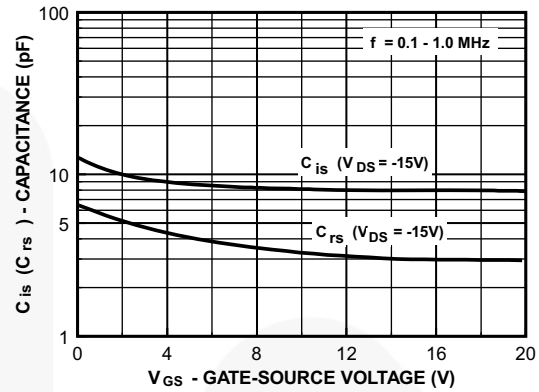


Figure 10. Capacitance vs. Voltage

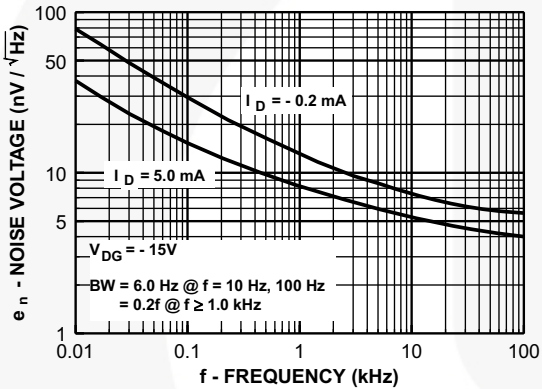


Figure 11. Noise Voltage vs. Frequency

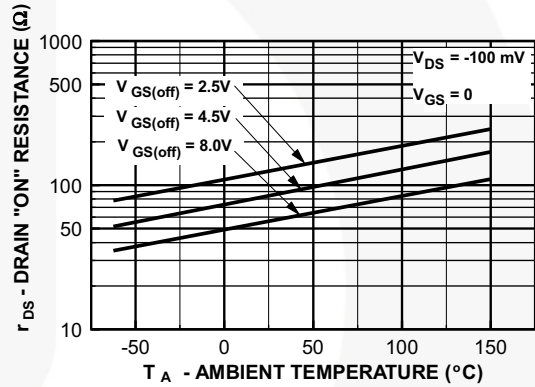


Figure 12. Channel Resistance vs. Temperature

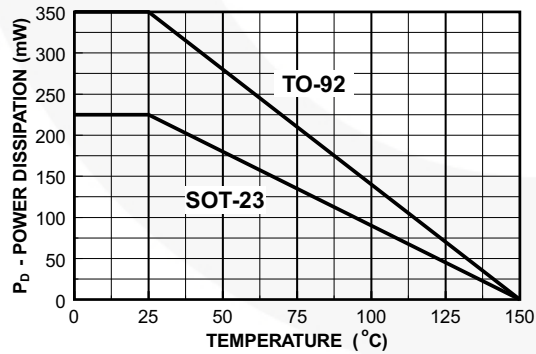
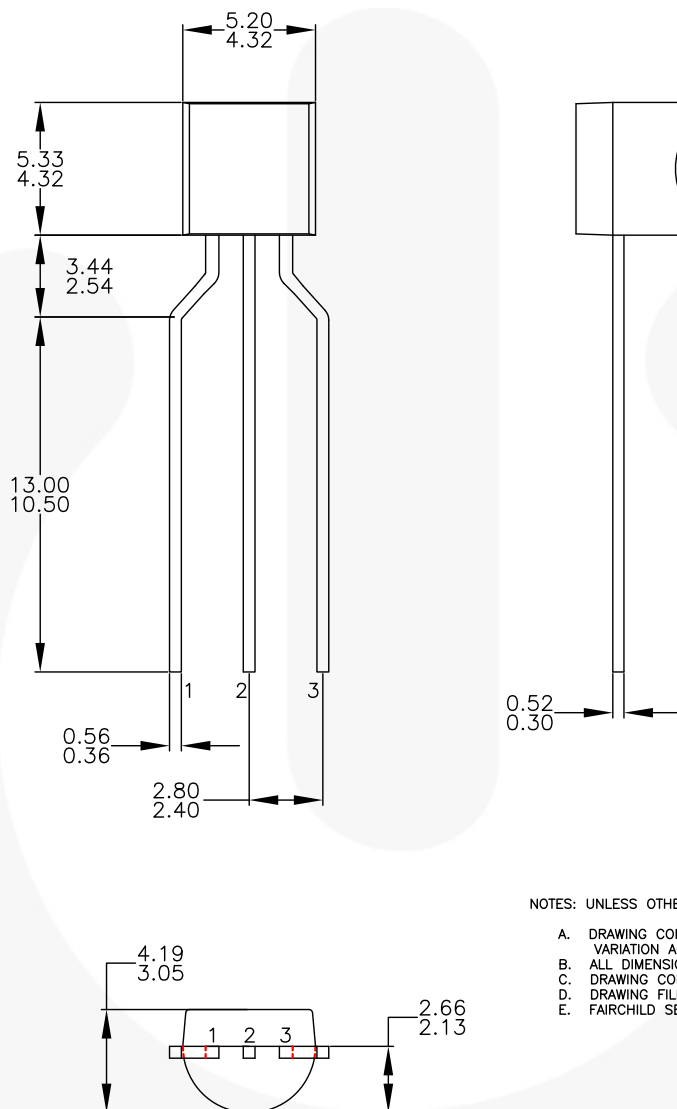


Figure 13. Power Dissipation vs. Ambient Temperature

Physical Dimensions

TO-92



NOTES: UNLESS OTHERWISE SPECIFIED

- A. DRAWING CONFORMS TO JEDEC MS-013, VARIATION AC.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5M-2009.
- D. DRAWING FILENAME: MKT-ZA03FREV3.
- E. FAIRCHILD SEMICONDUCTOR.

Figure 14. 3-LEAD, TO92, MOLDED, 0.200 IN LINE SPACING LEAD FORM (J61Z OPTION) (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/dwg/ZA/ZA03F.pdf>

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area:

http://www.fairchildsemi.com/packaging_dwg/PKG-ZA03F_BK.pdf

Physical Dimensions (Continued)

SOT-23

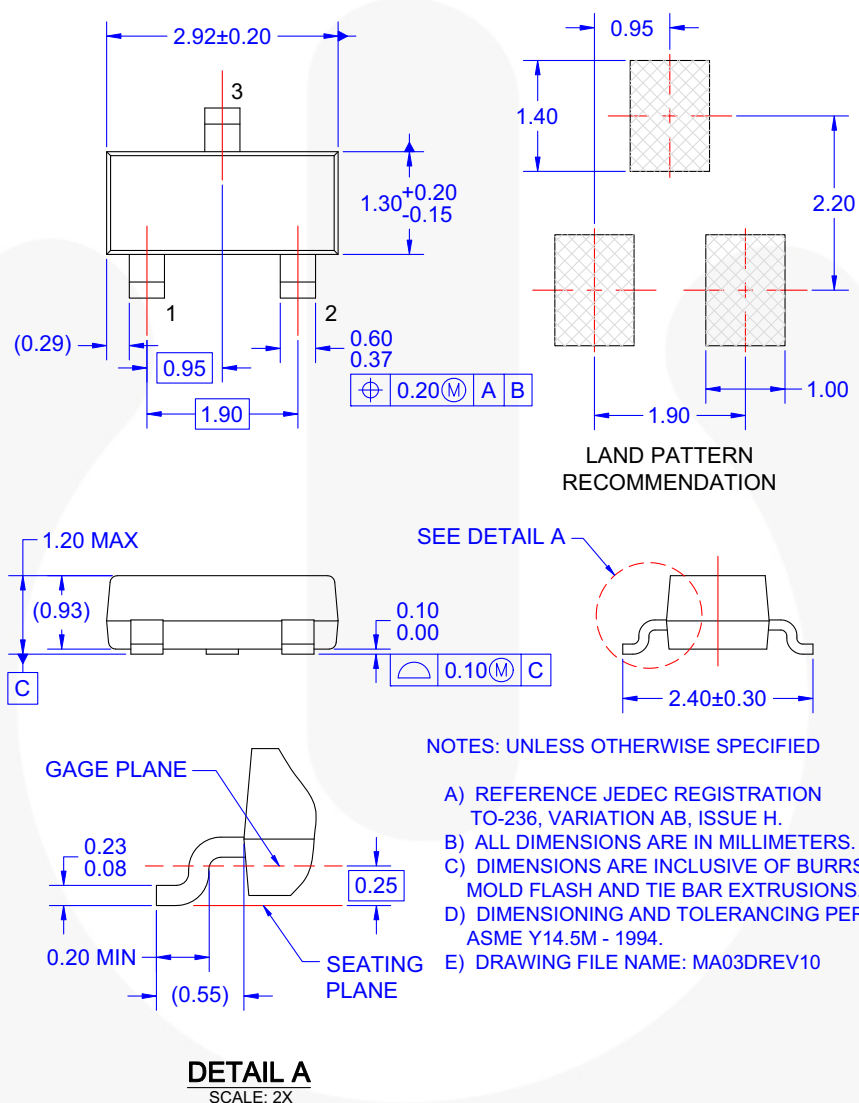


Figure 15. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:


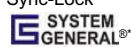



<http://www.fairchildsemi.com/dwg/MA/MA03D.pdf>

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area:

http://www.fairchildsemi.com/packaging_dwq/PKG-MA03D.pdf.

TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™	F-PFS™		Sync-Lock™
AX-CAP®*	FRFET®	PowerXS™	
BitSiC™	Global Power Resource SM	PowerTrench®	TinyBoost®
Build it Now™	GreenBridge™	PowerXS™	TinyBuck®
CorePLUS™	Green FPS™	Programmable Active Droop™	TinyCalc™
CorePOWER™	Green FPS™ e-Series™	QFET®	TinyLogic®
CROSSVOLT™	Gmax™	QS™	TINYOPTO™
CTL™	GTO™	Quiet Series™	TinyPower™
Current Transfer Logic™	IntelliMAX™	RapidConfigure™	TinyPWM™
DEUXPEED®	ISOPLANAR™		TinyWire™
Dual Cool™	Making Small Speakers Sound Louder and Better™	Saving our world, 1mW/W/kW at a time™	TranSiC™
EcoSPARK®	MegaBuck™	SignalWise™	TriFault Detect™
EfficientMax™	MICROCOUPLER™	SmartMax™	TRUECURRENT®*
ESBC™	MicroFET™	SMART START™	μSerDes™
	MicroPak™	Solutions for Your Success™	
Fairchild®	MicroPak2™	SPM®	UHC®
Fairchild Semiconductor®	MillerDrive™	STEALTH™	Ultra FRFET™
FACT Quiet Series™	MotionMax™	SuperFET®	UniFET™
FACT®	mWSaver®	SuperSOT™-3	VCX™
FAST®	OptoHiT™	SuperSOT™-6	VisualMax™
FastvCore™	OPTOLOGIC®	SuperSOT™-8	VoltagePlus™
FETBench™	OPTOPLANAR®	SupreMOS®	XS™
FPS™		SyncFET™	

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I66

AMEYA360

Components Supply Platform

Authorized Distribution Brand :



Website :

Welcome to visit www.ameya360.com

Contact Us :

➤ Address :

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd
Minhang District, Shanghai , China

➤ Sales :

Direct +86 (21) 6401-6692
Email amall@ameya360.com
QQ 800077892
Skype ameyasales1 ameyasales2

➤ Customer Service :

Email service@ameya360.com

➤ Partnership :

Tel +86 (21) 64016692-8333
Email mkt@ameya360.com